

Title (en)
ORGANOSILOXANES

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ORGANOSILOXANE

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ORGANOSILOXANES

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Application
EP 03796272 A 20030603

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• US 0317658 W 20030603
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Abstract (en)
[origin: WO2004037877A2] The present invention provides an organosiloxane comprising at least 80 weight percent of Formula I:
[Y0.01-1.0SiO1.5-2]a[Z 0.01-1.0SiO1.5-2]b[H0.01-1.0SiO1.5-2]c where Y is aryl; Z is alkenyl; a is from 15 percent to 70 percent of Formula I;
b is from 2 percent to 50 percent of Formula I; and c is from 20 percent to 80 percent of Formula I. The present organosiloxane may be used as
ceramic binder, high temperature encapsulant, and fiber matrix binder. The present composition is also useful as an adhesion promoter in that it
exhibits good adhesive properties when coupled with other materials in non-microelectronic or microelectronic applications. Preferably, the present
compositions are used in microelectronic applications as etch stops, hardmasks, and dielectrics.

IPC 1-7
C08G 77/12; **C08G 77/20**; **B05D 3/02**; **B05D 3/06**; **C23C 16/00**; **H01L 21/31**; **H01L 21/312**; **C09D 183/04**

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CPC (source: EP KR)
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H01L 21/76807 (2013.01 - EP); **H01L 2924/12044** (2013.01 - EP)

Citation (search report)
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WO 2004037877 A2 20040506; **WO 2004037877 A3 20050113**; **WO 2004037877 A9 20041111**; AU 2003298518 A1 20040513;
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